

• (0) 1 and (semiconductor and (die chip)

packag\$3 and (substrate near
(peripheral side peripheral near
side)) near (die chip)

	U	I	Document ID	Issue Date	Pages	Title	Current OR	Current xRef
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20040197954 A1	20041007	15	Chip scale image sensor semiconductor package and method of fabrication	438/108	
2	<input type="checkbox"/>	<input type="checkbox"/>	US 20040188829 A1	20040930	12	Package with integrated wick layer and method for heat removal	257/712	438/106
3	<input type="checkbox"/>	<input type="checkbox"/>	US 20040178499 A1	20040916	9	Semiconductor package with multiple sides having package contacts	257/734	
4	<input type="checkbox"/>	<input type="checkbox"/>	US 20040164386 A1	20040826	6	Unmolded package for a semiconductor device	257/678	
5	<input type="checkbox"/>	<input type="checkbox"/>	US 20040155337 A1	20040812	19	High density chip level package for the packaging of integrated circuits and	257/738	
6	<input type="checkbox"/>	<input type="checkbox"/>	US 20040150100 A1	20040805	14	Packaging of integrated circuits with carbon nano-tube arrays to enhance heat	257/720	
7	<input type="checkbox"/>	<input type="checkbox"/>	US 20040125580 A1	20040701	10	Mounting capacitors under ball grid array	361/794	361/760; 361/763
8	<input type="checkbox"/>	<input type="checkbox"/>	US 20040113250 A1	20040617	17	Integrated circuit assembly	257/680	257/723
9	<input type="checkbox"/>	<input type="checkbox"/>	US 20040070080 A1	20040415	15	Low cost, high performance flip chip package structure	257/778	257/E21.503; 257/E23.069;
10	<input type="checkbox"/>	<input type="checkbox"/>	US 20040043539 A1	20040304	8	Plastic ball grid array with integral heatsink	438/122	257/E23.092; 438/126
11	<input type="checkbox"/>	<input type="checkbox"/>	US 20040041271 A1	20040304	13	Methods for wafer-level packaging of microelectronic devices and microelectronic	257/759	257/723; 257/738;